



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **KIRA, et al.**

Group Art Unit: 2652

Serial No.: 09/548,313

Examiner: **Craig A. Renner**

Filed: **April 12, 2000**

**P.T.O. Confirmation No.: 6169**

For: **HEAD ASSEMBLY HAVING INTEGRATED CIRCUIT CHIP COVERED BY  
LAYER WHICH PREVENTS FOREIGN PARTICLE GENERATION**

**RESPONSE UNDER 37 CFR §1.116**

**RECEIVED**

**JUN 03 2003**

**MAILSTOP AF**

**Technology Center 2600**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

May 29, 2003

Sir:

In response to the Office Action dated **January 29, 2003**, extended to **May 29, 2003** by a  
**one month** Petition for Extension of Time, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Amend the claims to read as follows:

1. (Twice Amended) A head assembly comprising:

a mounting surface;

an integrated circuit chip which is mounted on the mounting surface and processes signals;

and

a head slider which is provided with a head and is mounted on the mounting surface,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the

*Do not  
enter  
APR 6-11-03*